EMSOFT 2015

International Conference on Embedded Software
October 4-9, 2015, Amsterdam, The Netherlands

EMSOFT 2015: Call for Papers

The ACM SIGBED International Conference on Embedded Software (EMSOFT) brings together researchers and developers from academia, industry, and government to advance the science, engineering, and technology of embedded software development. EMSOFT 2015 is part of the Embedded Systems Week. Since 2001, EMSOFT has been the premier venue for cutting-edge research in the design and analysis of software that interacts with physical processes, with a long-standing tradition for results on cyber-physical systems, which compose computation, networking, and physical dynamics.

EMSOFT 2015 (15th in the series!) is part of the Embedded Systems Week.

Program chairs:

Alain Girault, INRIA, Grenoble, France
Nan Guan, Northeastern University, China

Areas of Interest

- Design and implementation of embedded software
- Formal modeling and verification
- Testing and validation
- Model- and component-based software design and analysis
- Software technologies for safety-critical and mixed-critical systems
- Software architectures for cyber-physical systems
- Robust implementation of control systems
- Software for distributed, networked embedded systems
- Software development techniques for multi- and many-core systems
- Scheduling and execution time analysis
- Operating systems and middleware
- QoS management and performance analysis
- Energy-efficient embedded software
- Embedded software security
- Empirical studies and their reproduction, and confirmation
- Application areas, e.g., automotive, avionics, energy, health care, mobile devices, multimedia

Submission Information

Papers should represent original work, not published or submitted for publication in other forums. A blind review process will be enforced. Authors should not reveal authorship directly or indirectly through references. Papers must be in PDF format and should consist of a self-contained main part not exceeding 10 pages in ACM two-column format (9pt on 8.5"x11" letter size paper),and an optional supplement containing additional theoretical or experimental evidences that could be beneficial to the reviewer. Main paper and supplement shall be submitted in one file and together, and must not exceed 20 pages in total. **The supplement will not be part of the official proceedings.** For formatting instructions and templates, visit the ACM web site. Formal proceedings will be published on CD-ROM and web page forms (copyright by ACM and IEEE).

Important Dates

Abstract Submission
March 23, 2015 (11:59 pm GMT-12)

Full Paper Submission
March 30, 2015 (11:59 pm GMT-12)
(Firm deadline)

Notification of Paper Acceptance
June 08, 2015

Camera-ready version
July 13, 2015

Conference
October 4-9, 2015

TPC members:

Tarek Abdelzaher	UIUC, US
Karl-Erik Årzén	Lunds Universitet, Sweden
Sanjoy Baruah	University of North Carolina, US
Timothy Bourke	École Normale Supérieure, France
Björn Brandenburg	MPI-SWS, Germany
Samarjit Chakraborty	TU München, Germany
Wenguang Chen	Tsinghua University, China
Patricia Derler	University of California at Berkeley, US
Stephen Edwards	Columbia University, US
Petru Eles	Linköpings Universitet, Sweden
Rolf Ernst	TU Braunschweig, Germany
Marc Geilen	TU Eindhoven, The Netherland
Reinhard von Hanxleden	University of Kiel, Germany
Connie Heitmeyer	US Naval Research Laboratory, US
Hermann Härtig	TU Dresden, Germany
Shinpei Kato	Nagoya University, Japan
Tei-Wei Kuo	National Taiwan University, Taiwan
Edward Lee	University of California at Berkeley, US
Xuandong Li	Nanjing Univeristy, China
Giuseppe Lipari	Scuola Superiore Sant'Anna, Italy
Louis Mandel	IBM Research, US
Florence Maraninchi	Univ. Grenoble Alpes, France
Tulika Mitra	NUS, Singapore
Miroslav Pajic	University of Pennsylvania, US
Luigi Palopoli	University of Trento, Italy
Linh Thi Xuan Phan	University of Pennsylvania, US
Jan Reineke	Saarland University, Germany
Partha Roop	The Univ.of Auckland, New Zealand
Abhik Roychoudhury	NUS, Singapore
Sandeep Shukla	Virginia Tech, US
Robert de Simone	INRIA, France
Oleg Sokolsky	University of Pennsylvania, US
Aviral Shrivastava	Arizona State University, US
Wenyao Xu	SUNY Buffalo, US
Jason Xue	City University of Hong Kong, China
Jingling Xue	UNSW, Australia
Sergio Yovine	University of Buenos Aires, Argentina